



Material Content Data Sheet



Sales Product Name	SAK-XC2267M-104F80L AA			Issued		29. August 2013		
MA#	MA001021516							
Package	PG-LQFP-100-8			Weight*		755.66 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	38.601	5.11	5.11	51082	51082
leadframe	inorganic material	phosphorus	7723-14-0	0.069	0.01		91	
	non noble metal	zinc	7440-66-6	0.275	0.04		364	
	non noble metal	iron	7439-89-6	5.501	0.73		7279	
	non noble metal	copper	7440-50-8	223.351	29.56	30.34	295569	303303
wire	noble metal	gold	7440-57-5	2.766	0.37	0.37	3660	3660
encapsulation	organic material	carbon black	1333-86-4	2.316	0.31		3065	
	plastics	epoxy resin	-	62.527	8.27		82744	
	inorganic material	silicondioxide	60676-86-0	398.319	52.69	61.27	527113	612922
leadfinish	non noble metal	tin	7440-31-5	9.288	1.23	1.23	12292	12292
plating	noble metal	silver	7440-22-4	2.495	0.33	0.33	3302	3302
glue	plastics	epoxy resin	-	2.539	0.34		3360	
	noble metal	silver	7440-22-4	7.616	1.01	1.35	10079	13439
*deviation	< 10%	Sum in total:			100,00			1000000

Important Remarks:

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